



LEAD FREE ALLOY

Sn95.5 Ag3.8 Cu0.7

TSC LEAD FREE ALLOY – Lead Free Eutectic alloy for soldering printed circuits, produced from very high quality metals.

Chemical Characteristics

Amount of Tin:	95.5 +/- 0.5%
Amount of Silver:	3.8 +/- 0.3%
Amount of Copper:	0.7 +/- 0.2%
Tin and Silver Copper from first melting purity:	>99.95%.

Maximum content of impurities: see below:

Cd	Sb	Bi
<0.002%	<0.05%	<0.01%

Fe	Zn	Al	As
<0.02%	<0.001%	<0.001%	<0.01%

Pb	Other
<0.05%	<0.05%

Physical Characteristics:

Melting point	217°C Eutectic.
Specific weight	7.4
Working temperature	260 to 450°C.

Supplied as:

Bars	Extruded bars or sticks in cartons of 20 Kg (Exact Tare weight stated on carton).
Wire	On spools of 500gm, 1kg, 3kg, 15 Kgs. (others please contact us)
Quality Insurance	Certificates of conformity can be supplied with each lot if required.
Labelling	Cartons/containers labels show manufactured Lot Number and Alloy.

Storage:

- Original packaging at an average temperature of 20°C
- 12 months for flux cored wires.